

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A semiconductor device comprising:

a substrate which has a main surface; [[and]]

an alignment mark which is formed on the main surface and which has a pattern, wherein the pattern in a plane view has a shape that is obtained by eliminating corners from a polygon; and

an oxidation prevention cover film on the alignment mask and formed as having the pattern.

Claim 2 (Original): The semiconductor device as claimed in claim 1, wherein the polygon is a rectangle.

Claim 3 (Currently Amended): The semiconductor device as claimed in claim 1, wherein [[the]] a width of the pattern of the alignment mark ranges from 0.6 μm to 0.8 μm .

Claim 4 (Currently Amended): The semiconductor device as claimed in claim 1, wherein ~~the pattern of the alignment mark comprises~~ is a metal film.

Claims 5-6 (Canceled)

Claim 7 (Currently Amended): The semiconductor device as claimed in claim 1 ~~[[5]]~~, wherein ~~[[the]]~~ a width of the pattern of the oxidation prevention cover film is 1 μm to several μm wider ~~[[in]]~~ at one side than ~~[[the]]~~ a width of the pattern ~~formed~~ of the metal film alignment mark.

Claim 8 (Currently Amended): The semiconductor device as claimed in claim 1 ~~[[5]]~~, wherein the oxidation prevention cover film is formed of iridium-based metal.

Claim 9 (Currently Amended): A semiconductor device comprising:

a substrate which has a main surface; ~~[[and]]~~

an alignment mark which is formed on the main surface and which has first through fourth sub-patterns ~~sub-patterns~~,

wherein the first and second sub-patterns ~~sub-patterns~~ are arranged so as to oppose each other, ~~[[and]]~~ the third and fourth sub-patterns ~~forth sub-patterns~~ are arranged so as to oppose each other, and wherein the first through fourth sub-patterns ~~sub-patterns~~ are separated from one another; and

an oxidation prevention cover film on the alignment mark and formed as having the first through fourth sub-patterns.

Claim 10 (Currently Amended): The semiconductor device as claimed in claim 9, wherein ~~[[the]]~~ a width of the sub-patterns ~~sub-patterns~~ of the alignment mark ranges from 0.6 μm to 0.8 μm .

Claim 11 (Original): The semiconductor device as claimed in claim 9, wherein the alignment mark comprises a metal film.

Claims 12-13 (Canceled)

Claim 14 (Currently Amended): The semiconductor device as claimed in claim 9 ~~[[13]]~~, wherein ~~[[the]]~~ a width of the first through fourth sub-patterns of the oxidation prevention cover film ~~is~~ patterns are 1 μm to several μm wider ~~[[in]]~~ at one side than ~~[[the]]~~ a width of the ~~corresponding~~ first through fourth sub-patterns of the alignment mark ~~sub patterns~~.

Claim 15 (Currently Amended): The semiconductor device as claimed in claim 9 ~~[[12]]~~, wherein the oxidation prevention cover film is formed of iridium-based metal.

Claim 16 (New): A semiconductor device comprising:

a substrate having a main surface;

an alignment mark on the main surface of the substrate, wherein the alignment

mark is strip-like and has the shape of a polygon without corners along a plane parallel to the main surface of the substrate; and

an oxidation prevention cover film on the alignment mark, wherein the oxidation prevention cover film is strip-like and has annular shape along another plane parallel to the main surface of the substrate.

Claim 17 (New): The semiconductor device of claim 16, wherein the polygon is a rectangle.

Claim 18 (New): The semiconductor device of claim 17, wherein the oxidation prevention cover film has rectangular annular shape.

Claim 19 (New): The semiconductor device of claim 16, wherein the alignment mark has a width ranging from 0.6 μm to 0.8 μm .

Claim 20 (New): The semiconductor device of claim 16, wherein a width of the oxidation prevention cover film is 1 μm to several μm wider than a width of the alignment mark.

Claim 21 (New): The semiconductor device of claim 16, wherein the alignment mark is a metal film.

Claim 22 (New): The semiconductor device of claim 16, wherein the oxidation prevention cover film is an iridium based metal.